

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

## Notification# 20151215005 Datasheet for TMP275 Information Only

Date:12/16/2015To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN ww admin team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

### 20151215005 Information Only Attachments

# **Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

#### DEVICE

CUSTOMER PART NUMBER

TMP75AIDGKR TMP75AIDR TMP75AIDRG4 TMP75AIDGKT TMP75AID

#### null null null null null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20151215005				PCN Da	ate:	12/16/2015	
Title: Datasheet fo	or TMP175 and T	MP75						
ustomer Contact: PCN Manager				De	Dept:		Quality Services	
Change Type:					_		-	
Assembly Site		Design			Wafer	<sup>-</sup> Bum	p Site	
Assembly Process			et		Wafer	er Bump Material		
Assembly Materials		Part num	ber change		Wafer	<sup>-</sup> Bum	Bump Process	
	Mechanical Specification					Fab Site		
Packing/Shipping/Labeling		Test Proc	ess				Fab Materials	
					Wafer	<sup>-</sup> Fab I	Process	
		otificatio	on Details					
Description of Chan Texas Instruments Inc				-	1.0.1.			
he product datasheet he following change	.,			' <b>-</b>				
TEXAS						тир	175, TMP75	
INSTRUMENTS			SBOS288	-JANU	ARY 2004-R		DECEMBER 2015	
		-						
Changes from Revision K	(April 2015) to Revisi	on L					Page	
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com